

SOT1186-1

plastic, heatsink small outline package; 14 leads (flat)

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HSOP14F
Package type industry code	HSOP14F
Package style descriptive code	HSOP (heatsink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	20-9-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	15.8	-	15.9	16	mm
E	package width	10.9	-	11	11.1	mm
A	seated height	3	-	3.25	3.5	mm
A ₂	package height	3	-	3.15	3.3	mm
e	nominal pitch	-	-	1	-	mm
n ₂	actual quantity of termination	-	-	14	-	



2. Package outline

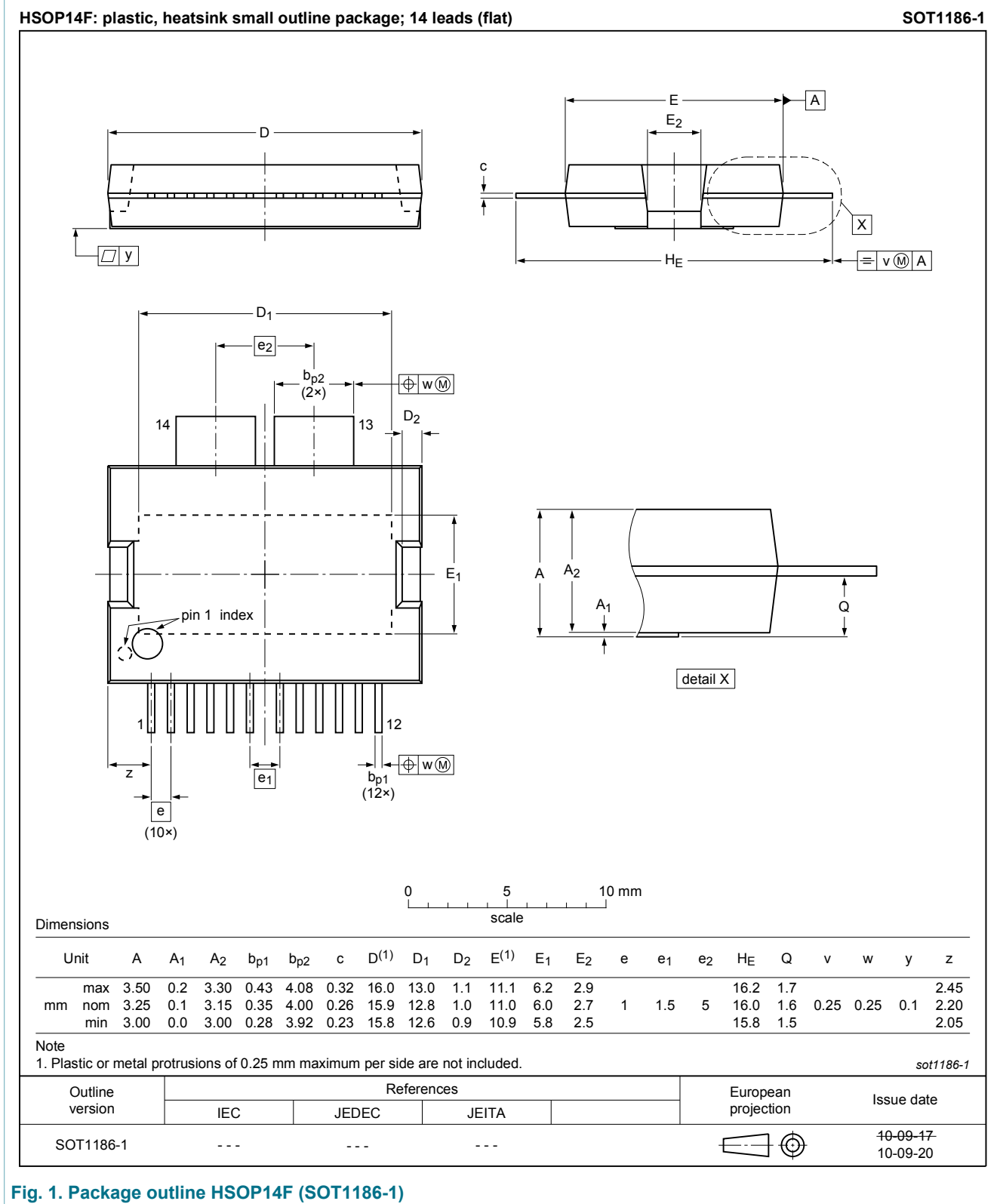


Fig. 1. Package outline HSOP14F (SOT1186-1)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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